

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number BZX38450-C5V6-Q Part Description										
									Nexperia DHAM			
									SMD package			
		Test Conditions	Duration	# Lots	# Quantity	# Rejects						
			TEST Pre- and Post-Stress									
		# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below				
# A1	PC Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	1514	64430	0						
# B1	HTRB	MIL-STD-750-1 M1038 Method A Tj = Tjmax, VR = 80 % of rated reverse voltage	1000 hours	250	11400	0						
# B1b	SSOP Steady State Operational	MIL-STD-750-1 M1038 Method B Tj = Tjmax, Iz = 100% of max. datasheet reverse current	1000 hours	44	1920	0						
# A4	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0						
# A3 or	UHAST Unbiased HAST	JESD22-A118 Tamb = 130 °C, RH = 85 % JESD22-A102 Tamb = 121 °C, RH = 100 %	— 96 hours	311	14080	0						
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)										
# A2 alk	H3TRB High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of	1000 have-	211	14000	0						
# A2 alt	IOL	MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔT_j =	1000 hours	311	14080	0						
# A5	Intermittent Operating Life	, .	1000 hours	312	14120	0						
# C8	RSH Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	269	8070	0						
# C10	SD Solderability	J-STD-002		19	6660	0						

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Zener	11400	0	0,37	2,68E+09

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